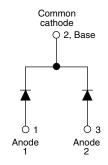


HEXFRED® Ultrafast Soft Recovery Diode, 2 x 16 A



TO-247AC 3L



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
I _{F(AV)}	2 x 16 A					
V_{R}	1200 V					
V _F at I _F	2.3 V					
t _{rr} typ.	30 ns					
T _J max.	150 °C					
Package	TO-247AC 3L					
Circuit configuration	Common cathode					

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

BENEFITS

- Reduced RFI and EMI
- · Reduced power loss in diode and switching transistor
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

DESCRIPTION

VS-HFA32PA120C... is a state of the art ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 1200 V and 16 A per leg continuous current, the VS-HFA32PA120C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the th portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA32PA120C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

MECHANICAL DATA

Case: TO-247AC 3L

Molding compound meets UL 94 V-0 flammability rating **Terminal:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Cathode to anode voltage	V_{R}		1200	V			
Maximum continuous forward current per leg	I_	T _C = 100 °C	16				
per device	I _F		32	Α			
Single pulse forward current	I _{FSM}	t _p = 10 ms	190	A			
Maximum repetitive forward current	I _{FRM}		64				
Maximum power dissipation	P _D	T _C = 25 °C	151	W			
iviaximum power dissipation		T _C = 100 °C	60	- vv			
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C			



ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS	
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		1200	-	-		
	V _{FM}	I _F = 16 A	See fig. 1	-	2.5	3.0	V	
Maximum forward voltage		I _F = 32 A		-	3.2	3.93		
		I _F = 16 A, T _J = 125 °C		ı	2.3	2.7		
Maximum reverse	1	$V_R = V_R$ rated	See fig. 2	-	0.75	20	- μΑ	
leakage current	I _{RM}	$T_J = 125 ^{\circ}\text{C}, V_R = 0.8 \text{x} V_R \text{rated}$	See lig. 2	-	375	2000		
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	27	40	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	8.0	-	nH	

DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Develop received time	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A}$	A/μs, V _R = 30 V	-	30	-		
Reverse recovery time See fig. 5, 10	t _{rr1}	T _J = 25 °C		-	90	135	ns	
See lig. 5, 10	t _{rr2}	T _J = 125 °C	$I_F = 16 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	164	245]	
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	5.8	10	- A	
See fig. 6	I _{RRM2}	T _J = 125 °C		-	8.3	15		
Reverse recovery charge	Q _{rr1}	$T_J = 25 ^{\circ}C$		-	260	675		
See fig. 7	Q _{rr2}	T _J = 125 °C		-	680	1838		
Peak rate of fall of recovery	dI _{(rec)M} /dt1	T _J = 25 °C		-	120	-		
current during t _b See fig. 8	dI _{(rec)M} /dt2	T _J = 125 °C		-	76	-	A/µs	

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Thermal resistance, junction to case	R _{thJC}		-	-	0.83			
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	40	K/W		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.50	-			
Weight			-	2.0	-	g		
vveignt			-	0.07	1	OZ.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-247AC 3L		HFA32F	PA120C			

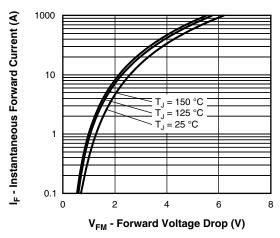


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

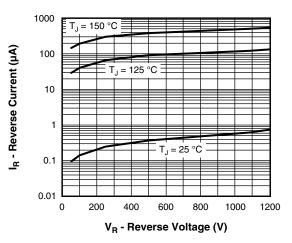


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

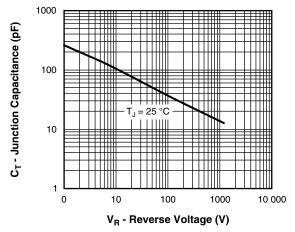


Fig. 3 - Typical Junction Capacitance vs.Reverse Voltage

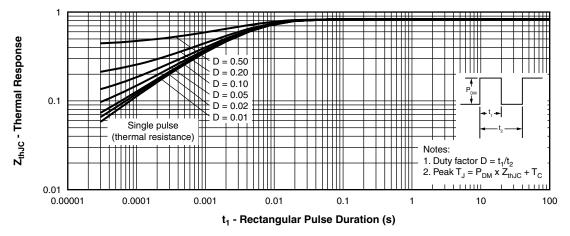


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

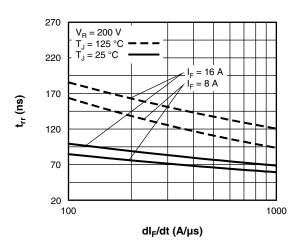


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

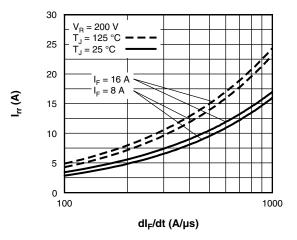


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

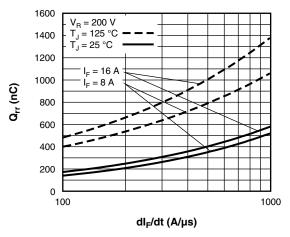


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

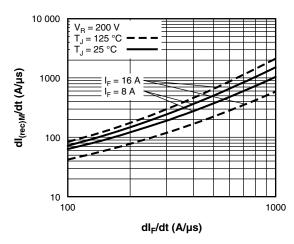
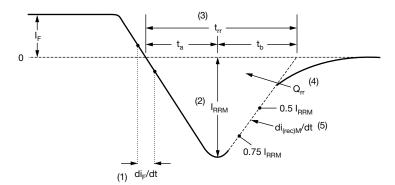


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

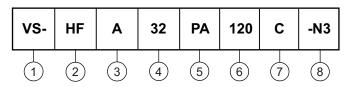
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - HEXFRED® family

Electron irradiated

Current rating (32 = 32 A)

5 - PA = TO-247AC, 3 pins

6 - Voltage rating: (120 = 1200 V)

C = common cathode

8 - Environmental digit:

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

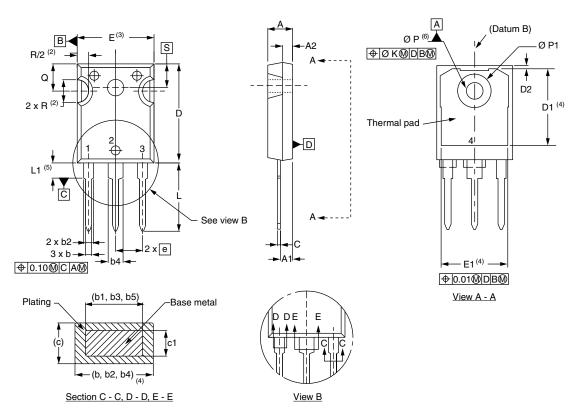
ORDERING INFORMATION (Example)							
PREFERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION							
VS-HFA32PA120C-N3	25	500	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96138				
Part marking information	www.vishay.com/doc?95007				



TO-247AC 3L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INCHES		NOTES	
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.65	5.31	0.183	0.209		
A1	2.21	2.59	0.087	0.102		
A2	1.17	1.37	0.046	0.054		
b	0.99	1.40	0.039	0.055		
b1	0.99	1.35	0.039	0.053		
b2	1.65	2.39	0.065	0.094		
b3	1.65	2.34	0.065	0.092		
b4	2.59	3.43	0.102	0.135		
b5	2.59	3.38	0.102	0.133		
С	0.38	0.89	0.015	0.035		
c1	0.38	0.84	0.015	0.033		
D	19.71	20.70	0.776	0.815	3	
D1	13.08	-	0.515	-	4	

SYMBOL	MILLIMETERS		INC	NOTES	
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.35	0.020	0.053	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	254	0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51	5.51 BSC		0.217 BSC	
	·		·	·	·

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension Q



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